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Orderable: N/A	Designed for: Public Release	Mod. Date: 4/10/2015
TID #: PMP9256	Project Title: LM5122 Isolated Synchronous Flyback	
Number: PMP9256	Rev: B	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 2
Drawn By:	File: PMP9256_REV_B_Sh1_SchDoc	Size: B
Engineer: Robert Sheehan	Contact: http://www.ti.com/support	

Revision History	
Revision	Notes
B	Update for PCB

H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C

DNP FID1 DNP FID2 DNP FID3

PCB Number: PMP9256
PCB Rev: B

PCB LOGO
Texas Instruments

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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